

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chang-Cheng Hung</td> <td>12/27/2006</td> </tr> <tr> <td>Tsai-Sheng Gau</td> <td>01/04/2007</td> </tr> </tbody> </table>		Name	Execution Date	Chang-Cheng Hung	12/27/2006	Tsai-Sheng Gau	01/04/2007
Name	Execution Date						
Chang-Cheng Hung	12/27/2006						
Tsai-Sheng Gau	01/04/2007						
RECEIVING PARTY DATA							
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.						
Street Address:	No. 8, Li-Hsin Road 6						
Internal Address:	Science-Based Industrial Park						
City:	Hsin-Chu						
State/Country:	TAIWAN						
Postal Code:	300-77						
PROPERTY NUMBERS Total: 1							
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11671772</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11671772		
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Application Number:	11671772						
CORRESPONDENCE DATA							
Fax Number:	(214)200-0853						
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>							
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NAME OF SUBMITTER:	David M. O'Dell						

Total Attachments: 2
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CH \$40.00 11671772

ASSIGNMENT

WHEREAS, we,

- (1) Chang-Cheng Hung of No. 16, Alley 2, Lane 58, Sinsheng Street
Jhubei City, Hsinchu County 203, Taiwan, R.O.C.
- (2) Tsai-Sheng GAU of No. 35, Lane 4, An-Kang Street
Hsinchu City, Taiwan, R.O.C.

have invented certain improvements in

METHOD AND SYSTEM FOR WAFER INSPECTION

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and

X filed on February 6, 2007 and assigned application number 11/671,772; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Miaoli City, Miaoli County, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal,

substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chang-Cheng Hung

Residence Address: No. 16, Alley 2, Lane 58, Sinsheng Street
Jhubei City, Hsinchu County 203, Taiwan, R.O.C.

Dated: 12/27/06

Chang-Cheng Hung
Inventor Signature

Inventor Name: Tsai-Sheng GAU

Residence Address: No. 35, Lane 4, An-Kang Street
Hsinchu, Taiwan, R.O.C.

Dated: 1/4, 2007

Tsai-Sheng Gau
Inventor Signature
